

Metal Thermal Interface Materials

Enhance Thermal Performance with Our Metal Thermal Interface Materials



Solder TIM Solutions

Reflowed solder joints are thermally conductive because of the intermetallic bond. A low-voiding joint has better thermal performance.



Heat-Spring®

A compressible interface between a heat source and a heat-sink; the surface of a Heat-Spring® is patterned to reduce contact resistance.



Liquid Metal & Phase Change Metal Alloys

Indium Corporation offers multiple practical liquid metal or PCMA's. They possess high thermal conductivity and low interfacial resistance against most surfaces.



Indium TIM Solutions for Burn-In

Indium is used as a high-performance TIM because of its high thermal conductivity (86W/mK). A thin aluminum layer can prevent indium from adhering to the DUT surface.

Common thermal interface material alloys: Indalloy®4 (100In), Indalloy®1E (52In/48Sn), Indalloy®290 (97In/3Ag), Indalloy®3 (90In/10Ag), Indalloy®51E, Indalloy®300E, Indalloy®306



Contact our engineers: askus@indium.com

Learn more: www.indium.com/TIMs

From One Engineer To Another®

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

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